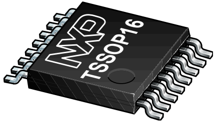


SOT403-1

plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch, 5 mm x 4.4 mm x 1.1 mm body

10 December 2019 **Package information**

1 Package summary

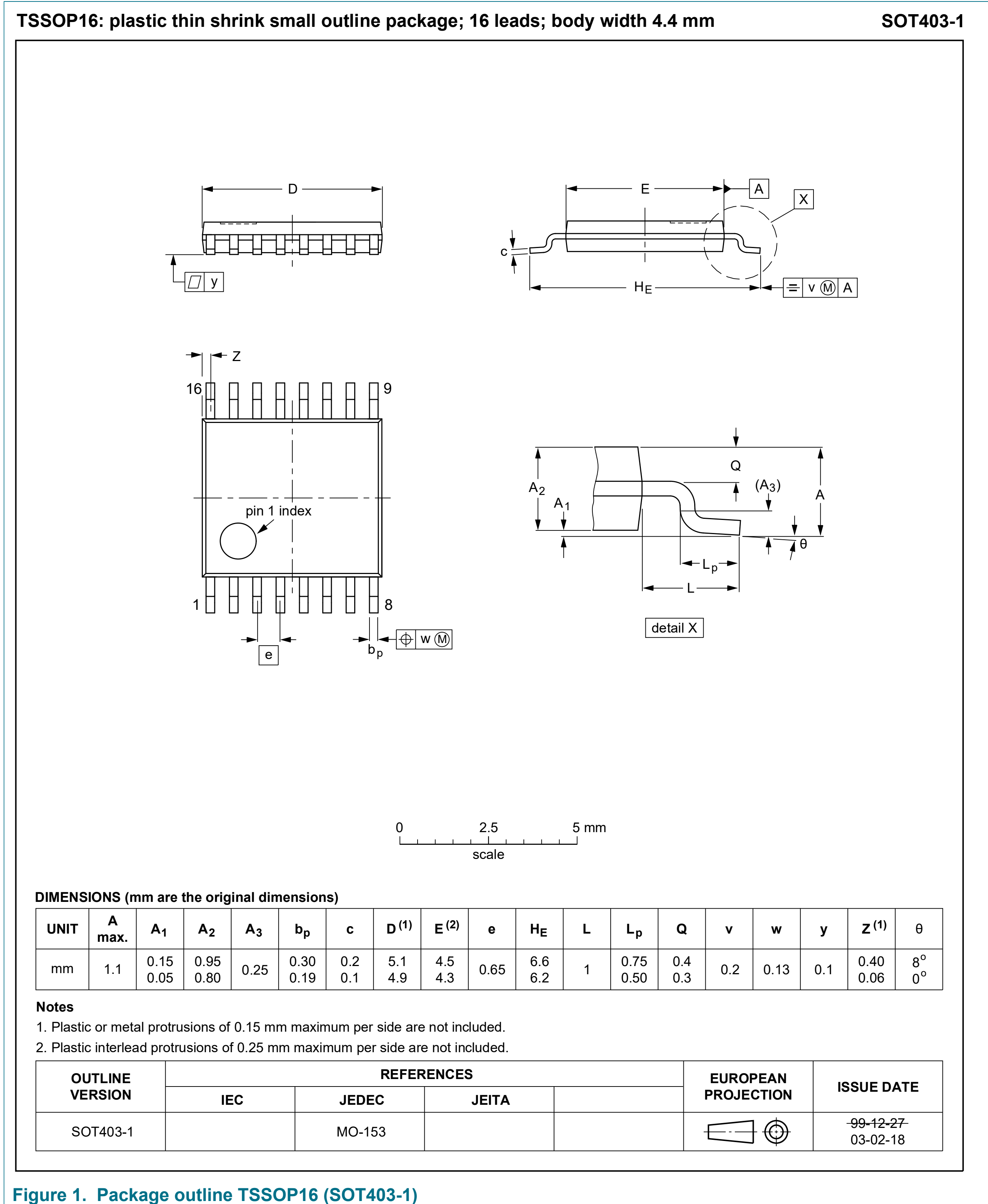
Terminal position code	D (double)
Package type descriptive code	TSSOP16
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	10-12-2019
Manufacturer package code	SOT403-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.3	4.4	4.5	mm
seated height	-	-	1.1	mm
package height	0.8	0.9	0.95	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	16	-	

2 Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D [1]	E [2]	e	H_E	L	L_p	Q	v	w	y	Z [1]	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Figure 1. Package outline TSSOP16 (SOT403-1)

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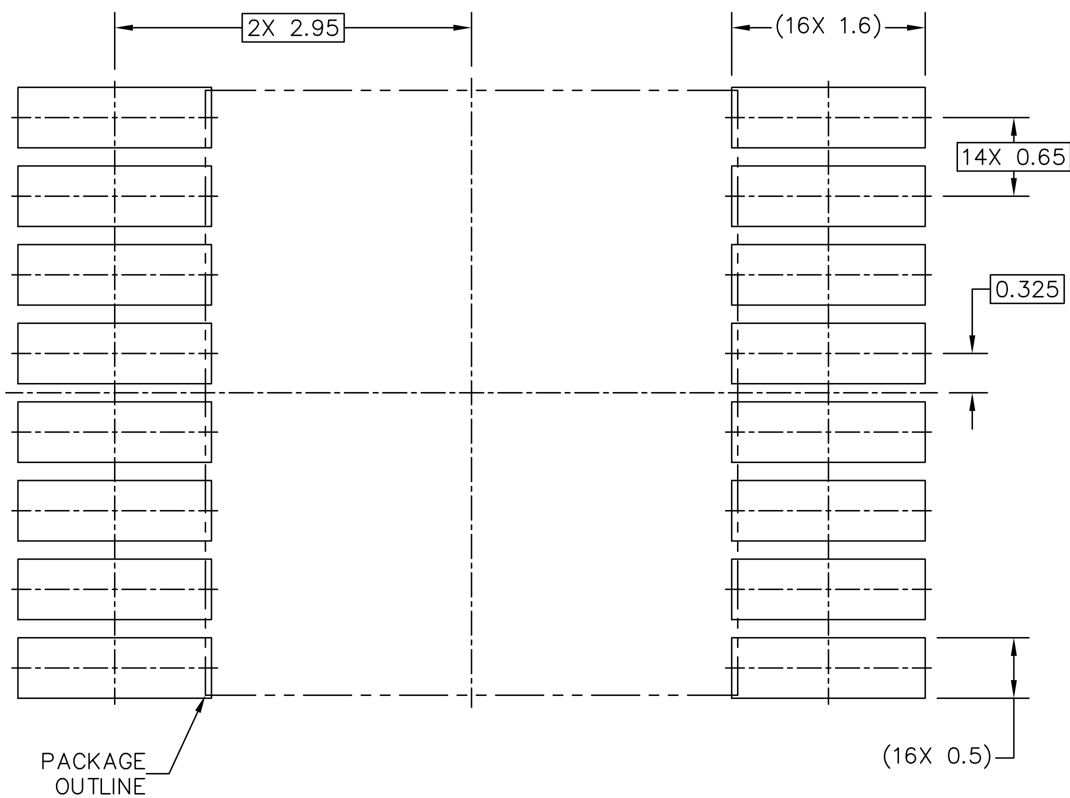
3 Soldering

PDSO−G−16 I/O
4.4 X 5 X 1.1 PKG, 0.65 PITCH

SOT403−1



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DATE: 28 NOV 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO−153	DRAWING NUMBER:	REVISION:	PAGE:

Figure 2. Reflow soldering footprint part1 for TSSOP16 (SOT403-1)

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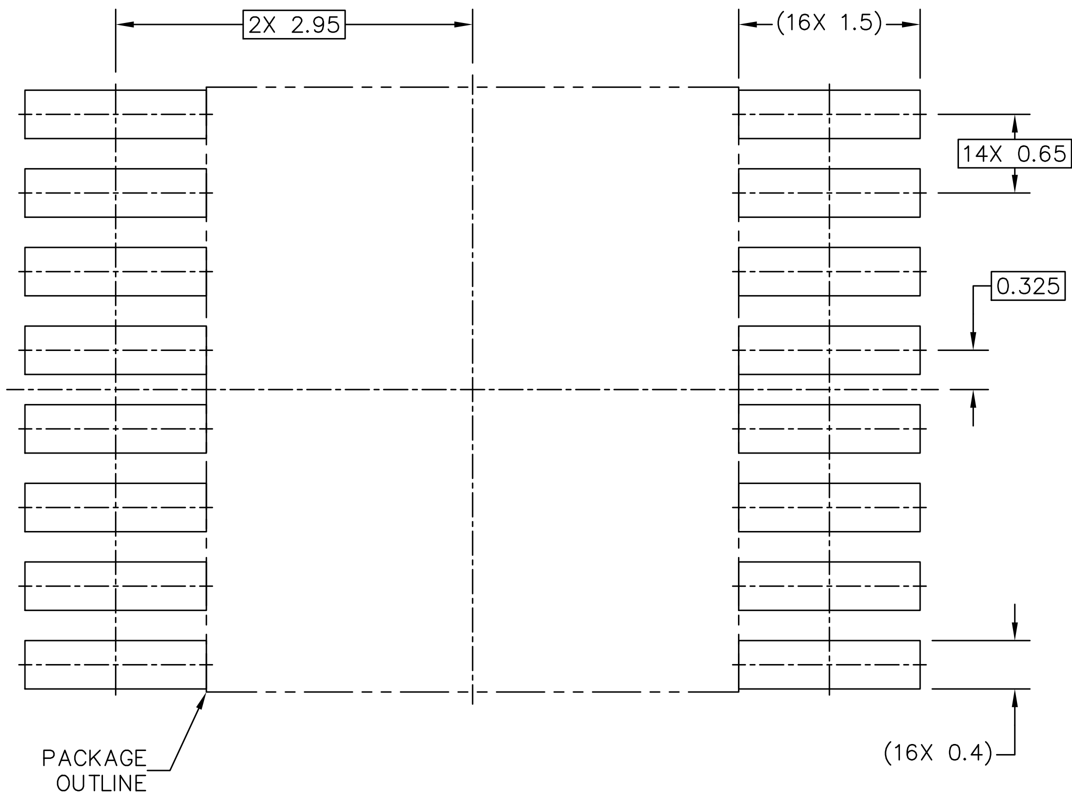
PDSO-G-16 I/O
4.4 X 5 X 1.1 PKG, 0.65 PITCH

SOT403-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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Figure 3. Reflow soldering footprint part2 for TSSOP16 (SOT403-1)

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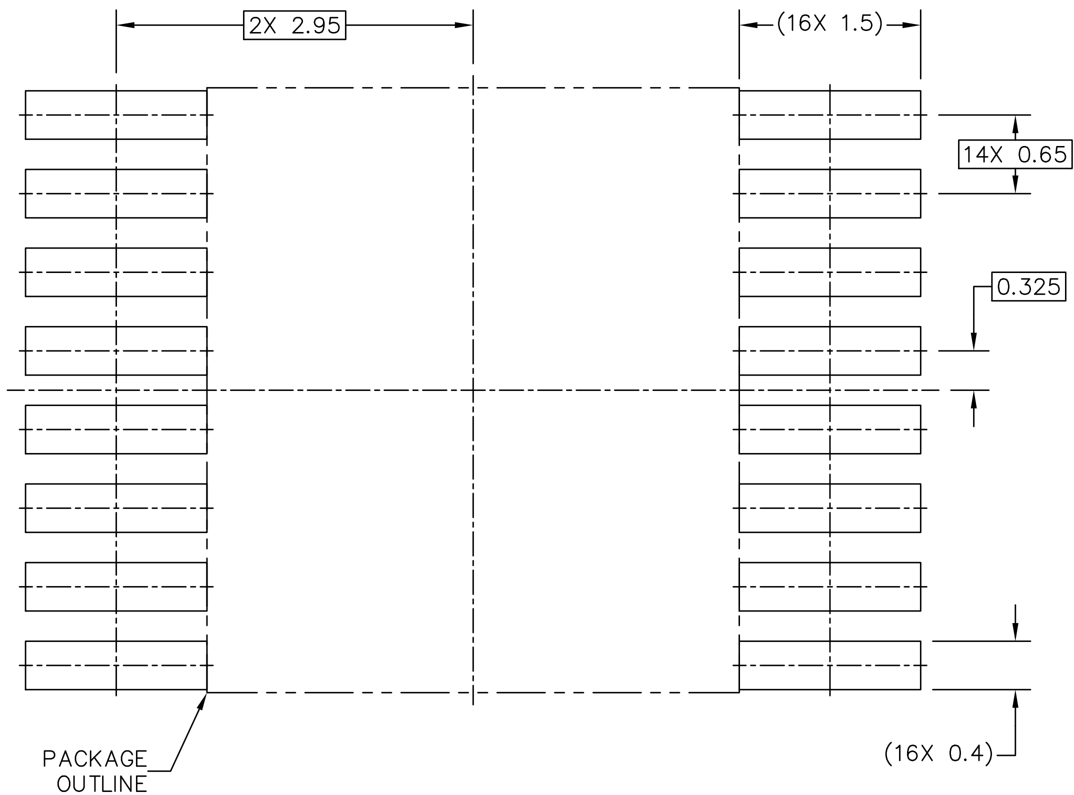
PDSO-G-16 I/O
4.4 X 5 X 1.1 PKG, 0.65 PITCH

SOT403-1



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.150

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-153	DRAWING NUMBER:	REVISION:	PAGE:

Figure 4. Reflow soldering footprint part3 for TSSOP16 (SOT403-1)

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4 Legal information

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